The richness and history of electronic and electro-optical packaging technology are illustrated in the above collage. It shows a ceramic circuit board in the background, overlaid on the upper right by a photograph of a gate rupture on an integrated circuit caused by a single radiation event. On the left is an indium bump used for electronic or electro-optical chips attached at cryogenic temperatures. The graph is from Gordon Moore’s original work (circa 1965) on the past and future progress on the evolution of integrated circuits.